

News Release

Unisem Reports Revenue of RM322.0 million (approx. US\$79.4 million) and Net Profit of RM38.8 million (approx. US\$9.6 million) for Third Quarter 2016

Kuala Lumpur, 3 November 2016 – Unisem (M) Berhad today announced results for the third quarter ended 30 September 2016 (**3Q16**).

Unisem recorded a consolidated revenue and net profit of RM322.0 million (approx. US\$79.4 million) and RM38.8 million (approx. US\$9.6 million) respectively for 3Q16. These represent decline of 2.3 percent and 4.5 percent in revenue and net profit respectively against the corresponding quarter ended 30 September 2015 (**3Q15**).

For the nine months period ended 30 September 2016 (**9m16**), the Group recorded revenue and net profit of RM960.6 million (approx. US\$235.3 million) and RM111.8 million (approx. US\$27.4 million) respectively, these represent increase of 5.7 percent in revenue and 16.3 percent in net profit as compared to the corresponding period a year ago (**9m15**).

The increase in revenue for 9m16 was mainly attributable to improved average selling prices arising from the appreciation of US\$/RM and US\$/RMB exchange rates, as compared to the prevailing rates in 9m15. The improvement in net profit for 9m16 was mainly due to higher foreign exchange gain and lower interest expense as compared to 9m15.

Group earnings before interest, tax, depreciation and amortization (EBITDA) for 3Q16 came in at about RM85.6 million (approx. US\$21.1 million), EBITDA margin was about 26.6 percent. Equipment capacity utilization averaged at about 76 percent for the Group in 3Q16. Group capital expenditure incurred in 3Q16 was about RM29.8 million (approx. US\$7.3 million), principally for purchase of equipment for advanced packaging activities.

Commenting on the outlook of the Group, Mr. John Chia Sin Tet, the group managing director said, "We expect the performance of the Group to remain satisfactory till the end of the financial year"

About Unisem

Unisem is a global provider of semiconductor assembly and test (OSAT) services for many of the world's most successful electronics companies. We offer an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding; a wide range of leadframe and substrate IC packaging; wafer level CSP; and RF, analog, digital, and mixed signal test. Our turnkey services include design, assembly, test, failure analysis, and electrical, mechanical, and thermal characterization and modeling. Unisem is an established MEMS OSAT with several years of experience in volume consumer and automotive production, in addition to a broad package portfolio covering multiple applications. The company has factory locations in lpoh, Malaysia; Chengdu, People's Republic of China; and in Batam, Indonesia. Unisem is headquartered in Kuala Lumpur, Malaysia. For more information about the company, its products and services, please visit its website at www.unisemgroup.com